

APPLICATION DATA SHEET

Electronic Version v14

Stylesheet Version v14.0

Title of Invention	A Printed-Circuit-Board (PCB) Module with a Milled-Back Insulator Layer around Flat Metal Pads for Surface-Mounting to a Larger Board
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Application Type : regular, utility

Attorney Docket Number : PS-117

Request Not To Publish

I/We hereby request that the attached application not be published under 37 U.S.C. 122(b).

I/We hereby certify that the invention disclosed in the attached application has not and will not be the subject of an application filed in another country, or under a multilateral agreement, that requires publication at eighteen months after filing.

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as our attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.